



CHIP SCALE MANUFACTURING

Electronics Manufacturing Learning Center

Overview

To meet the demand for smaller footprints, improved electrical performance and/or higher input/output in a given space, manufacturers are investigating advanced packaging technologies. This course will allow students to make informed decisions about advanced packaging technologies (flip-chips, chip scale packages, wire bonding, microBGAs and BGAs) based upon companies' needs.

Who Should Attend

Engineering and manufacturing managers, process engineers, technicians, machine operators and trainers responsible for making next-generation manufacturing decisions in the company.

Course Content

Topics covered are:

- ◆ Basic overview of die fabrication and chip scale packages
- ◆ Production implementation of flip chip and chip scale processes, including BGAs and microBGA
- ◆ Wire bonding and die placement techniques
- ◆ Underfill/encapsulation
- ◆ Inspection technologies
- ◆ Rework processes
- ◆ Uses of advanced packages & manufacturing assemblies in today's market

Benefits

- ◆ Hands-on training on advanced packaging equipment located within our demonstration factory
- ◆ Identify and perform critical process steps when manufacturing BGAs, microBGAs, flip chips, and chip scale packages
- ◆ Identify and implement process control methods and practices when manufacturing assemblies with advanced packages

Duration

Three days

Registration

Contact the EMPF Learning Center at:
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